

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIDEHIRO YANAI	08/04/2015
SHIN HIYAMA	08/04/2015
TOSHIYA SHIMADA	08/04/2015
YUKINORI ABURATANI	08/04/2015
RECEIVING PARTY DATA	
Name:	HITACHI KOKUSAI ELECTRIC INC.
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City:	TOKYO
State/Country:	JAPAN
Postal Code:	101-8980
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14838682
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NAME OF SUBMITTER:	DANIEL N. CALDER
SIGNATURE:	/Daniel N. Calder/
DATE SIGNED:	08/28/2015
Total Attachments: 5	

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COMBINED DECLARATION AND ASSIGNMENT

With respect to the invention titled

PLASMA PROCESSING APPARATUS AND METHOD OF MANUFACTURING
SEMICONDUCTOR DEVICE,

title

the undersigned has authorized the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application No.: 14/838,682 filed on August 28, 2015

I state and declare the following.

DECLARATION

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

ASSIGNMENT

The undersigned hereby authorizes assignee or assignee's representative to insert the Application Number and the filing date of this application if they are unknown at the time of execution of this assignment.

Assignee	<u>HITACHI KOKUSAI ELECTRIC INC.</u>
Assignee State or Country of Incorporation	<u>Japan</u>
Assignee Address	<u>14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan</u>

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, the application for United States Letters Patent entitled as above, and all divisions and continuations thereof, and in all letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignee, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

This Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name Hidehiro YANAI

Inventor's Signature Hidehiro Yanai

Date August 4, 2015

Signed at Toyama, Japan
(City and Country)

**SUPPLEMENTAL SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name Shin HIYAMA

Inventor's Signature Shin Hiyama

Date August 4, 2015

Signed at Toyama, Japan
(City and Country)

**SUPPLEMENTAL SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name Toshiya SHIMADA

Inventor's Signature Toshiya Shimada

Date August 4, 2015

Signed at Toyama, Japan
(City and Country)

**SUPPLEMENTAL SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name Yukinori ABURATANI

Inventor's Signature *Yukinori Aburatani*

Date *August 4, 2015*

Signed at Toyama, Japan
(City and Country)